

## AEC/APC Virtual Symposium Asia 2021 SPONSORSHIP

### November 4, 2021, Japan

Hidetaka Nishimura  
Chairman, AEC/APC Symposium Asia 2021 Executive Committee  
Renesas Electronics Corporation

Hidenori Kakinuma  
Chairman, AEC/APC Symposium Asia 2021 Program Committee  
Kioxia Corporation

It is our great pleasure to announce that the 8<sup>th</sup> annual AEC/APC Symposium Asia 2021 will be held on November 4, 2021 which is sponsored by ISSM (International Symposium on Semiconductor Manufacturing). AEC/APC Symposium Asia committee has made a decision to have the symposium as an **online symposium** due to this COVID-19 pandemic.

The program is consist of keynote speech, tutorial speeches, oral speeches, poster presentations and supplier exhibition.

This year, the symposium puts the subtitle" "AEC/APC in the SX / DX era" - Solving issues and contributing to innovations through the data science-"".

AEC/APC Symposium Asia continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We would like you to cooperate with us by supporting the AEC/APC Symposium Asia 2021.

Please see the benefit of AEC/APC Symposium Asia 2021 sponsorship.

#### Conference Overview

Date: November 4, 2021

Sponsored by: International Symposium on Semiconductor Manufacturing (ISSM)

Supported by: Japan Electronics and Information Technology Industries Association  
Semiconductor Equipment Association of Japan (SEAJ)  
Semiconductor Equipment and Materials International (SEMI)

In conjunction with: Dry Process Symposium (DPS)

Area of Interest: Equipment and Process Control

- FDC (Fault detection and classification)
- SPC (Statistical process control)
- Run-to-run Control
- RMS (Recipe Management System)
- Model-based Process Control
  - Physical and chemical process models
  - Soft sensor
  - Virtual metrology
- Tool Data Acquisition and Analysis
  - Data collection
  - Sensor development
  - Failure and Yield Analysis
  - Statistical approaches
  - Bigdata Analysis
  - AI, Machine Learning
  - Enhanced equipment quality Assurance
- APC Strategy
  - Future Needs and opportunities
  - SDGs (Sustainable Development Goals)
  - Standard
- Region Expansion
  - Back-end process
  - MEMS (MEMS)
  - Display device
  - Solar panel
  - Battery

## About AEC/APC Symposium

AEC/APC symposium calls its annual conference in North America, Europe, and Asia. The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in the process technology of LCD, PV and Battery.

In Japan, the 8th conference is called in this year. Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium is a very good chance among the technical authorities from Japan and from out of Japan to share their knowledge and technologies in AEC/APC area. The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss.

Today, this area already forms the core part of the manufacturing engineering technology.

The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

\*AEC: Advanced Equipment Control, APC: Advanced Process Control

## Organization

### **Japan Executive Committee**

Chair	Hidetaka Nishimura	Renesas Electronics Corporation
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### **Japan Program Committee**

Chair	Hidenori Kakinuma	Kioxia Corporation
Vice-Chair	Sumika Arima	University of Tsukuba
Members	Takashi Kurosawa	Azbil Corporation
	Akira Kagoshima	Hitachi High-Tech Corporation
	Osamu Ohishi	IBM Japan Digital Services Company
	Koh Horimoto	IBM Japan Digital Services Company
	Hirofumi Tsuchiyama	INFICON Co.,Ltd
	Senichi Nishibe	KLA-Tencor Japan Ltd.
	Kenji Miyake	PMT Corporation
	Tsuyoshi Miyatake	Renesas Electronics Corporation
	Shunichi Shibuki	Sony Semiconductor Manufacturing Corporation
	Koichi Sakamoto	Tokyo Electron Ltd.
	Hisato Tanaka	Tokyo Electron Ltd.
	Kazutaka Nagashima	Toshiba Electronic Devices & Storage Corporation
	Tomoya Tanaka	Tower Partners Semiconductor Co., Ltd.
Takahiro Tsuchiya	United Semiconductor Japan Co., Ltd.	

	Platinum	Gold	Silver	Bronze
Sponsorship Fee	¥800,000	¥500,000	¥300,000	¥80,000
<b>AEC/APC Symposium Asia 2021 Invitation (Free)</b>				
Free ticket(s) for AEC/APC Symposium Asia 2021(Tutorial session excluded)	12	7	4	1
<b>AEC/APC Symposium Asia 2021 Website and Virtual Platform</b>				
Company logo placed on homepage	Yes	Yes	Yes	Yes
Link to company homepage on homepage	Yes	Yes	Yes	Yes
Company logo placed on Platform	Yes	Yes	Yes	Yes
Link to company home on platform	Yes	Yes	Yes	Yes
<b>AEC/APC Symposium Asia 2021 Proceedings (Download)</b>				
Company logo on the proceedings (PDF) (User would need to have Internet access when viewing the proceedings)	Yes	Yes	Yes	Yes
<b>Others</b>				
Participants' list (name, email, affiliation, only accepted participants)	Yes	Yes	No	No
Virtual Booth (on the platform)	Yes	Yes	Yes	Yes
Booth Visitors' list (name, email, affiliation, only accepted participants)	Yes	Yes	Yes	Yes
Promotion Movie Broadcast	Yes	Yes	Yes	Yes
Promotion Movie Broadcast Session Attendees' list (name, email, affiliation, only accepted participants)	Yes	Yes	Yes	Yes
Promotion Movie Broadcast	Yes	Yes	Yes	Yes

**Contact:**

AEC/APC Symposium Asia 2021 Office

C/O Semiconductor Portal, Inc.

E-mail: [aecapc\\_2021@semiconportal.com](mailto:aecapc_2021@semiconportal.com)